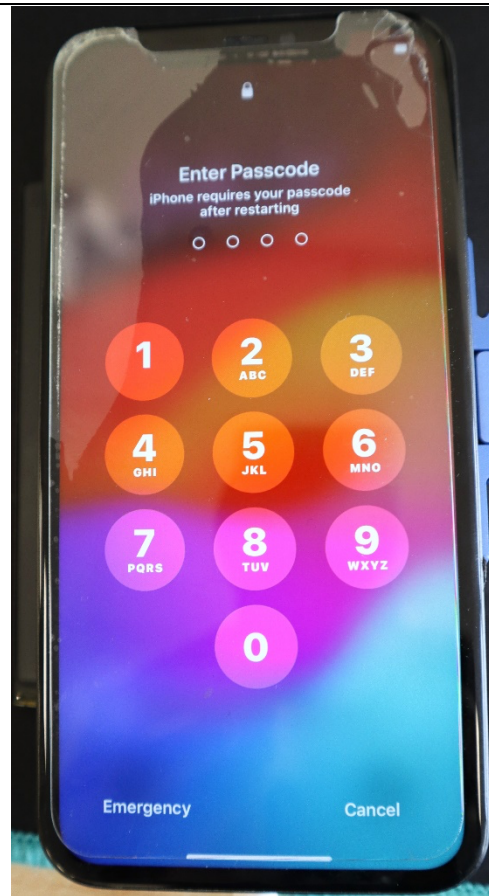The AP board was then attached to donor peripheral components (screen, charging port and battery) to ensure a full boot was possible. This was completed without the RF board present, to prevent any cellular connections. The phone was prompted to boot with a USB lightning cable attached to a wall outlet to prevent any data communication. The phone booted correctly to the pin code screen identifying the CPU/NAND and EEPROM swap had been a success (Picture Ref 6.2.20)

To prevent the 3-minute reboot issue the AP & RF logic board required soldering back together with the AP board being attached to the interposer attached to the RF logic board.
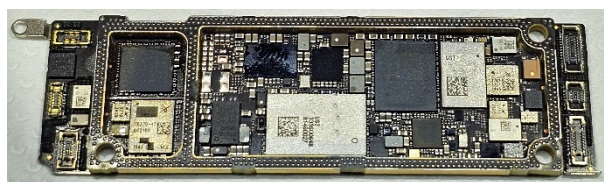

Picture Ref 6.2.20: CPU Swap Test.JPG

The RF logic board was placed into a specialist stencil (picture Ref 6.2.21) and low-melt solder paste added. Heat was then introduced to melt the solder paste and complete the reball process (Picture Ref 6.2.22).

Picture Ref 6.2.21: RF Logic Board Reball – Stencil.JPG

Picture Ref 6.2.22: RF Board Reballed.JPG